


## Full Material Declaration for attached parts list

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	<p><b>Diotech Semiconductor AG</b>  DUNS number: 330866844  -, Kreuzmattenstr. 4, Heitersheim, 79423, Germany  Declarations authorised by:  Udo Steinebrunner, Product Manager, -</p>
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Declaration effective from: 19 October 2022 [Approved on 03 February 2026, 13:08 GMT]

## Materials and substances

Use/Location	Material Group	% w/w of material in the part	Substances in the material	CAS Number	% w/w of substance in the material
Chip (die)	Other inorganic materials	4.31%	Silicon	7440-21-3	100%
Die attach	Sn-Pb solder	1.75%	Silver	7440-22-4	2.5%
			Tin	7440-31-5	5%
			<b>Lead</b> EU RoHS Exemption 7(a) Exempt from other regulatory requirements Exempt from other regulatory requirements	7439-92-1	92.5%
Encapsulation	EP (Epoxy resin)	52.42%	Carbon black	1333-86-4	0.5%
			ZINC BORATE	1332-07-6	4%
			Phenol, polymer with formaldehyde	9003-35-4	8%
			Formaldehyde, polymer with (chloromethyl)oxirane and 2-methylphenol	29690-82-2	10%
			Quartz sand	60676-86-0	77.5%
Leadfinish	Tin plating	0.64%	Tin	7440-31-5	100%
Leadframe	Copper (e.g. copper amounts in cable harnesses)	40.88%	Copper	7440-50-8	100%

## Attached parts list

Part number	Part name	Part Mass	Part Mass UoM
SOD-123FL (EB) H-free	Diode SMD	0.01717	g

